



# GENERAL INSTRUMENT

Technical Specifications  
May, 1965

## P CHANNEL-ENHANCEMENT MODE SILICON INSULATED GATE FIELD EFFECT TRANSISTOR

**MEM 511**  
TENTATIVE

Silicon P-Channel, Insulated — Gate Enhancement Mode Field Effect Transistor Designed Primarily For Low-Power Audio, Radio Frequency and Commutating Applications.

### FEATURES:

- $10^{10}$  ohms input resistance
- Integrated zener clamp — protects the gate
- Normally off with zero gate voltage
- Square Law linear transfer characteristics

### APPLICATIONS:

- High input impedance amplifiers
- Series and shunt choppers
- Operational amplifiers
- Logic circuits
- RF and IF amplifiers

### CASE STYLE:

See Drawing

### MAXIMUM RATINGS:

( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

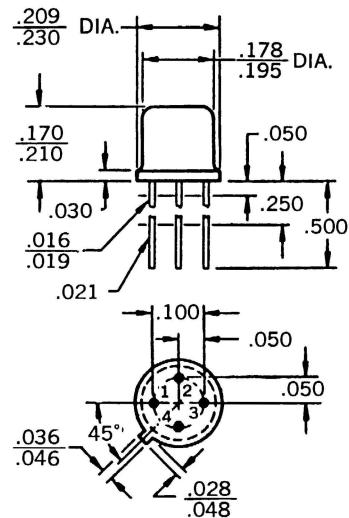
Drain to Source Voltage	.....	-30V
Gate to Source Voltage	.....	-30V
Gate to Drain Voltage	.....	-30V
Drain Current	.....	-50mA
Gate Current (Forward Direction for Zener Clamp)	.....	+0.1mA
Storage Temperature	.....	-50 to 150°C
Operating Junction Temperature	.....	-50 to 125°C
Total Dissipation at 25°C Case Temperature	.....	650mW
Total Dissipation at 25°C Ambient Temperature	.....	225mW

### ELECTRICAL CHARACTERISTICS:

( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS
$V_{GS}$	Gate Source Cutoff Voltage	-3	-6	.....	Volts	$V_{GS} = V_{DS}, I_D = 10\mu\text{A}$
$I_{DSS}$	Drain Leakage Current	.....	10	na	.....	$V_{DS} = -20\text{V}, V_{GS} = 0$
$I_{GSS}$	Gate Leakage Current	.....	1	na	.....	$V_{GS} = -15\text{V}, V_{DS} = 0$
$I_{D(on)}$	Drain Current	-3	.....	.....	ma	$V_{GS} = V_{DS} = 10\text{V}$
$BV_{DSS}$	Drain-Source Breakdown	-30	.....	.....	Volts	$I_D = 10\mu\text{A}, V_{GS} = 0$
$Y_{fs}$	Transadmittance	1000	1000	.....	$\mu\text{mho}$	$1\text{KC}, V_{GS} = V_{DS} = 10\text{V}$
$C_{gs}$	Gate to Source Capacitance	.....	3	.....	$\mu\text{mho}$	$10\text{MC}, V_{GS} = V_{DS} = 10\text{V}$
$C_{gd}$	Gate to Drain Capacitance	.....	2.5	.....	pf	$V_{GS} = V_{DS} = 10\text{V}$
$C_{ds}$	Drain to Source Capacitance	.....	2.0	.....	pf	$V_{GS} = V_{DS} = 10\text{V}$
$r_{ds(on)}$	Drain to Source Resistance	250	.....	.....	ohms	$V_{GS} = -15\text{V}, I_D = -1\text{mA}$

### 4 LEAD TO-18 TYPE PACKAGE



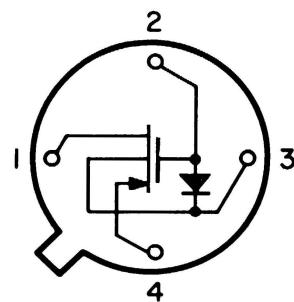
Bottom view

Note: All dimensions in inches.

### TERMINAL DIAGRAM

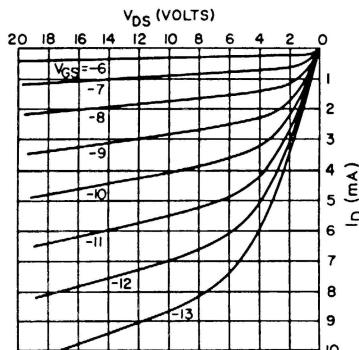
Lead

1. Drain
2. Gate
3. Body (Case)
4. Source

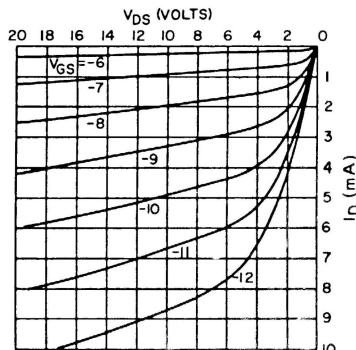


## TYPICAL CHARACTERISTIC CURVES

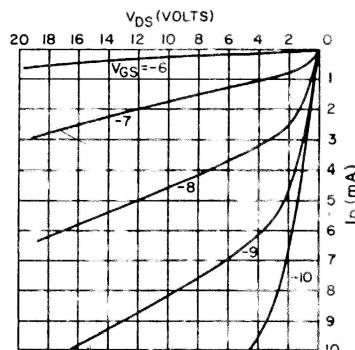
DRAIN CHARACTERISTICS AT +125°C



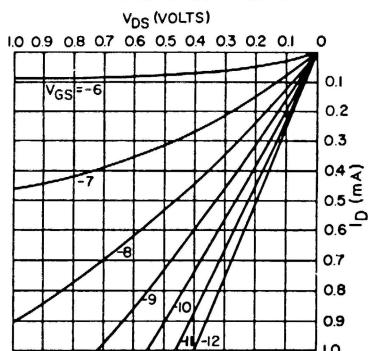
DRAIN CHARACTERISTICS AT 25°C



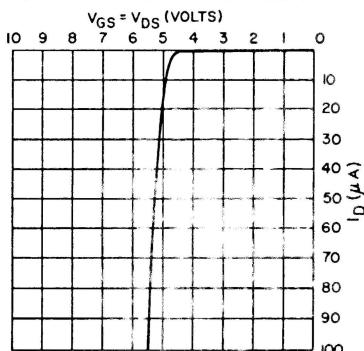
DRAIN CHARACTERISTICS AT -200°C



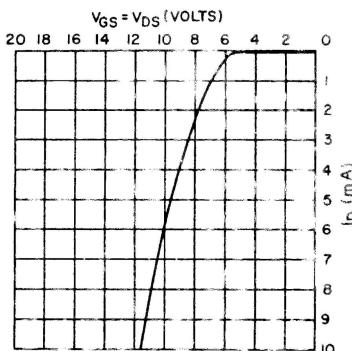
DRAIN CHARACTERISTICS AT 25°C



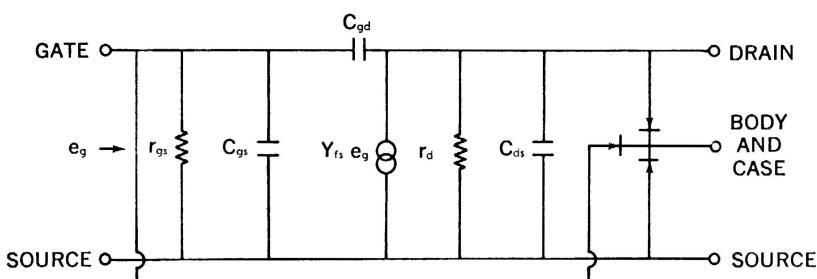
TURN-ON CHARACTERISTICS AT 25°C



TURN-ON CHARACTERISTICS AT 25°C



## SMALL SIGNAL EQUIVALENT CIRCUIT (Conditions: $V_{GS} = V_{DS} = 10V$ )



SYMBOL		TYPICAL VALUE	UNITS
Diodes	All diodes are to be considered perfect diodes		
$r_{gs}$	Gate to source leakage resistance and diode leakage resistance	$10^{10}$	ohms
$r_d$	Dynamic drain resistance	25	Kohms
$C_{gs}$	Gate to source capacitance	2.25	pf
$C_{gd}$	Gate to drain capacitance	1.5	pf
$C_{ds}$	Drain to source capacitance	1.25	pf
$Y_{fs}$	Forward transadmittance	2500	$\mu\text{mho}$

## HANDLING PRECAUTIONS

The MEM 511 insulated gate field effect transistors have been designed with an integrated zener diode clamp from the high input resistance ( $10^{15}$  ohm typical) gate, to the body which is internally connected to the case. This clamp eliminates the detrimental effects of high electrostatic voltages on the gate that can be generated in normal handling.

It is recommended that the body (lead 3) be connected to the source (lead 4) for most applications.

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